

AUG 20 2008

OK TO ENTER: /MK/

Application Number 10/730,878  
Amendment dated April 11, 2008  
Response to Office Action mailed January 17, 2008

### AMENDMENTS TO THE SPECIFICATION

Please replace paragraph [0033] of Applicant's originally-filed application with the following amended paragraph:

[0033] In some embodiments of the invention, overmold 106 encases all modules 103, 104 and 105. In other embodiments, overmold 106 is disposed over or around the modules without encasing the modules. Overmold 106 integrates modules 103, 104 into a desired form factor, but, where flexible, allows relative intermodule motion. In further embodiments, overmold 106 acts as a "frame" to hold the modules in a fixed position relative to one another, but does not fully cover the modules. Some features of the overmold, and variations on the shape of the overmold, are presented below. In general, the shape of the overmold depends upon the arrangement of the modules. The overmold may be made of a variety of materials, such as flexible silicone. The overmold may also include a rigid polymer such as Ticothane surrounded by flexible silicone. The invention is not limited to these materials, however, and the overmold may comprise any combination of elastomeric and/or non-elastomeric materials.